

Product Change Notification

(Notification – P2203015-DI)

(IMO-AZ-22-0002-1 / IMO-AZ-22-0004-1 / IMO-AB-22-0016-1 /
IMO-AB-22-0020-1 / IMO-AB-22-0014-1 / IMO-AB-22-0022-1)

March 31, 2022

To: *Our Valued Customer (Insert Customer Name Here)*

The purpose of this notification is to communicate a product change of select Renesas Electronics America, Inc. (REA) devices.

This notification announces one or more of the following assembly changes for select M16C and M32C devices.

1. Bonding Wire Change from Au to Cu
2. Lead Frame Change
3. Additional Mold Compound
4. Solder Paste Change from SnCu to Sn
5. Top Mark Change
6. Assembly Site Reduction from RSB & ATJ to RSB only

The “Change Notes” in the part list outlines the specific change(s).

Some devices have new part numbers, other devices will have no change to the part number. There is no impact to form, fit, quality & reliability of the products.

Affected Products: A review of our records indicates the list of products in the appendix may affect your company.

Part numbers given in this list are for active part numbers in REA database at the time of this notification.

Key Dates:

Shipments from REA of the parts with the assembly material changes begins.
--

November 1, 2022

Response: No response is required. REA will consider this notification approved 30 days after its issue. If you anticipate volumes beyond your regular rate prior to the transition date, please contact your REA sales representative with a forecast of your requirements.

If the customer provides a timely acknowledgement, the customer shall have 90 days (an additional 60 days) from the date of receipt of this notification in which to make any objections to the notification. If the customer does not make any objections to this notification within 90 days of the receipt of the notification, then Renesas will consider the notification as approved. If customer cannot accept the notification, then the customer must provide Renesas with a last time buy demand and purchase order.

Please contact your REA sales representative for any questions or comments. Thank you for your attention.

Sincerely,

Renesas Electronics America, Inc.

Appendix A: Affected Part Numbers

Booking Part Number	Replacement PN	Change Notes
M30260F3AGP#U3A	M30260F3AGP#33A	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 1);
M30260F3AGP#U5A	M30260F3AGP#35A	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 1);
M30260F3AGP#U7A	M30260F3AGP#37A	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 1);
M30260F6AGP#U3A	M30260F6AGP#33A	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 1);
M30260F6AGP#U5A	M30260F6AGP#35A	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 1);
M30260F6AGP#U7A	M30260F6AGP#37A	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 1);
M30260F6AGP#W9A	M30260F6AGP#59A	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 6);
M30260F6BGP#U9A	M30260F6BGP#39A	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 1);
M30260F8AGP#U3A	M30260F8AGP#33A	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 1);
M30260F8AGP#U5A	M30260F8AGP#35A	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 1);
M30260F8AGP#U7A	M30260F8AGP#37A	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 1);
M30260F8AGP#U9A	M30260F8AGP#39A	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 1);
M30260F8BGP#U3A	M30260F8BGP#33A	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 1);
M30260M6A-XXXGP#U5	M30260M6A-XXXGP#35	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 1);
M30280F6HP#U5B	M30280F6HP#35B	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 2);
M30280F6HP#U9B	M30280F6HP#39B	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 2);
M30280F8HP#U3B	M30280F8HP#33B	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 2);
M30280F8HP#U5B	M30280F8HP#35B	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 2);
M30280FAHP#U3B	M30280FAHP#33B	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 2);
M30280FAHP#U5B	M30280FAHP#35B	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 2);
M30280FAHP#U7B	M30280FAHP#37B	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 2);
M30280FAHP#U9B	M30280FAHP#39B	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 2);
M30280FCHP#U3B	M30280FCHP#33B	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 2);
M30280FCHP#U5B	M30280FCHP#35B	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 2);
M30280FCHP#U7B	M30280FCHP#37B	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 2);
M30280FCHP#U9B	M30280FCHP#39B	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 2);
M30290FAHP#U3A	M30290FAHP#33A	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 2);
M30290FAHP#U5A	M30290FAHP#35A	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 2);
M30290FCHP#U3A	M30290FCHP#33A	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 2);
M30290FCHP#U5A	M30290FCHP#35A	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 2);
M30290FCHP#U7A	M30290FCHP#37A	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 2);
M30290FCHP#U9A	M30290FCHP#39A	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 2);
M30302FAPGP#U3	M30302FAPGP#33	Additional Mold Compound; Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3); Assembly Site Reduction (RSB & ATJ to RRSB Only
M30302FAPGP#U5	M30302FAPGP#35	Additional Mold Compound; Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3); Assembly Site Reduction (RSB & ATJ to RRSB Only
M30302FCPGP#U3	M30302FCPGP#33	Additional Mold Compound; Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3); Assembly Site Reduction (RSB & ATJ to RRSB Only
M30302FCPGP#U5	M30302FCPGP#35	Additional Mold Compound; Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3); Assembly Site Reduction (RSB & ATJ to RRSB Only

Appendix A: Affected Part Numbers (cont.)

Booking Part Number	Replacement PN	Change Notes
M30302FEPGP#U3	M30302FEPGP#33	Additional Mold Compound; Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3); Assembly Site Reduction (RSB & ATJ to RRSB Only)
M30302FEPGP#U5	M30302FEPGP#35	Additional Mold Compound; Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3); Assembly Site Reduction (RSB & ATJ to RRSB Only)
M30302GAPGP#U5	M30302GAPGP#35	Lead Frame Change (Frame B to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3); Assembly Site Reduction (RSB & ATJ to RRSB Only)
M30302SPGP#U5	M30302SPGP#35	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3);
M3030RFAPGP#U5	M3030RFAPGP#35	Lead Frame Change (Frame B to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3); Assembly Site Reduction (RSB & ATJ to RRSB Only)
M3030RFCPGP#U5	M3030RFCPGP#35	Lead Frame Change (Frame B to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3); Assembly Site Reduction (RSB & ATJ to RRSB Only)
M3030RFGPGP#U3	M3030RFGPGP#33	Lead Frame Change (Frame B to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3); Assembly Site Reduction (RSB & ATJ to RRSB Only)
M3030RFGPGP#U5	M3030RFGPGP#35	Lead Frame Change (Frame B to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3); Assembly Site Reduction (RSB & ATJ to RRSB Only)
M30620FCPGP#U3C	M30620FCPGP#33C	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3);
M30620FCPGP#U5C	M30620FCPGP#35C	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3);
M30620FCPGP#U9C	M30620FCPGP#39C	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3);
M30620MCP-095GP#U3	M30620MCP-095GP#33	Lead Frame Change (Frame B to Frame C); Solder Paste Change (SnCu to Sn);
M30620MCP-599GP#U0	M30620MCP-599GP#30	Lead Frame Change (Frame B to Frame C); Solder Paste Change (SnCu to Sn);
M30620MCP-D01GP#U3	M30620MCP-D01GP#33	Lead Frame Change (Frame B to Frame C); Solder Paste Change (SnCu to Sn);
M30620SPGP#U3C	M30620SPGP#33C	Lead Frame Change (Frame B to Frame C); Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3);
M30620SPGP#U5C	M30620SPGP#35C	Lead Frame Change (Frame B to Frame C); Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3);
M30622F8PGP#U3C	M30622F8PGP#33C	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3);
M30622F8PGP#U5C	M30622F8PGP#35C	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3);
M30622M6P-XXXGP#U0	M30622M6P-XXXGP#30	Lead Frame Change (Frame B to Frame C); Solder Paste Change (SnCu to Sn);
M30622M6P-XXXGP#U3	M30622M6P-XXXGP#33	Lead Frame Change (Frame B to Frame C); Solder Paste Change (SnCu to Sn);
M30622M8P-XXXGP#U0	M30622M8P-XXXGP#30	Lead Frame Change (Frame B to Frame C); Solder Paste Change (SnCu to Sn);
M30622MEP-D27GP#U3	M30622MEP-D27GP#33	Solder Paste Change (SnCu to Sn);
M30622SPGP#U5C	M30622SPGP#35C	Lead Frame Change (Frame B to Frame C); Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3);
M30624FGPGP#U3C	M30624FGPGP#33C	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3);
M30624FGPGP#U5C	M30624FGPGP#35C	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3);
M30624FGPGP#U7C	M30624FGPGP#37C	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3);
M30624FGPGP#U9C	M30624FGPGP#39C	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3);
M30624MGP-XXXGP#U3	M30624MGP-XXXGP#33	Solder Paste Change (SnCu to Sn);
M30626FHPGP#U9C	M30626FHPGP#39C	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3);
M30626FHPGP#UJC	M30626FHPGP#3JC	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 7);
M30626FJPGP#U3C	M30626FJPGP#33C	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3);
M30626FJPGP#U5C	M30626FJPGP#35C	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3);
M30626FJPGP#U7C	M30626FJPGP#37C	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3);

Appendix A: Affected Part Numbers (cont.)

Booking Part Number	Replacement PN	Change Notes
M3062LFGPGP#U3C	M3062LFGPGP#33C	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3);
M3062LFGPGP#U5C	M3062LFGPGP#35C	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3);
M3062LFGPGP#U7C	M3062LFGPGP#37C	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3);
M3062LFGPGP#U9C	M3062LFGPGP#39C	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3);
M30800SAGP-BL#U5	M30800SAGP-BL#35	Solder Paste Change (SnCu to Sn);
M30840SGP#U5	M30840SGP#35	Solder Paste Change (SnCu to Sn);
M30843FHGP#U5	M30843FHGP#35	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 5);
M30843FJGP#U5	M30843FJGP#35	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 5);
M30843FWGP#U5	M30843FWGP#35	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 5);
M30853FHGP#U5	M30853FHGP#35	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 5);
M30853FJGP#U5	M30853FJGP#35	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 5);
M30873FHAGP#U5	M30873FHAGP#35	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 5);
M30873FHBGP#U5	M30873FHBGP#35	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 5);
M30873FHGP#U5	M30873FHGP#35	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 5);
M30876FJAGP#U5	M30876FJAGP#35	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 5);
M30876FJBGP#U5	M30876FJBGP#35	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 5);
M30879FKBGP#U5	M30879FKBGP#35	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 5);
M30879FLAGP#U5	M30879FLAGP#35	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 5);
M30879FLBGP#U5	M30879FLBGP#35	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 5);
M30879FLGP#U5	M30879FLGP#35	Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 5);
M308A0SGP#U5	M308A0SGP#35	Additional Mold Compound; Solder Paste Change (SnCu to Sn);
R5F363AKDFB#U0	R5F363AKDFB#30	Bond Wire Material Change (Au to Cu); Lead Frame Change (Frame A to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only)
R5F363AKNFB#30	No PN Change	Lead Frame Change (Frame A to Frame C); Additional Mold Compound;
R5F363AMDFB#30	No PN Change	Lead Frame Change (Frame A to Frame C); Additional Mold Compound;
R5F363AMDFB#U0	R5F363AMDFB#30	Bond Wire Material Change (Au to Cu); Lead Frame Change (Frame A to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only)
R5F363AMNFB#30	No PN Change	Lead Frame Change (Frame A to Frame C); Additional Mold Compound;
R5F3640DDFB#30	No PN Change	Additional Mold Compound;
R5F3640DDFB#U0	R5F3640DDFB#30	Bond Wire Material Change (Au to Cu); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only)
R5F3640DNFB#30	No PN Change	Additional Mold Compound;
R5F3640MCNFB#30	No PN Change	Lead Frame Change (Frame A to Frame C); Additional Mold Compound;
R5F3640MDFB#U0	R5F3640MDFB#30	Bond Wire Material Change (Au to Cu); Lead Frame Change (Frame B to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only)
R5F3640MNFB#U0	R5F3640MNFB#30	Bond Wire Material Change (Au to Cu); Lead Frame Change (Frame B to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only)
R5F364A6DFB#U0	R5F364A6DFB#30	Bond Wire Material Change (Au to Cu); Lead Frame Change (Frame A to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only)
R5F364A6NFB#30	No PN Change	Lead Frame Change (Frame A to Frame C); Additional Mold Compound;
R5F364A6NFB#U0	R5F364A6NFB#30	Bond Wire Material Change (Au to Cu); Lead Frame Change (Frame A to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only)
R5F364AEDFB#30	No PN Change	Lead Frame Change (Frame A to Frame C); Additional Mold Compound;

Appendix A: Affected Part Numbers (cont.)

Booking Part Number	Replacement PN	Change Notes
R5F364AEDFB#U0	R5F364AEDFB#30	Bond Wire Material Change (Au to Cu); Lead Frame Change (Frame A to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only)
R5F364AENFB#30	No PN Change	Lead Frame Change (Frame A to Frame C); Additional Mold Compound;
R5F364AENFB#U0	R5F364AENFB#30	Bond Wire Material Change (Au to Cu); Lead Frame Change (Frame A to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only)
R5F364AENFB#V2	R5F364AENFB#30	Bond Wire Material Change (Au to Cu); Lead Frame Change (Frame A to Frame C); Additional Mold Compound;
R5F364AKNFB#30	No PN Change	Lead Frame Change (Frame A to Frame C); Additional Mold Compound;
R5F364AMDFB#30	No PN Change	Lead Frame Change (Frame A to Frame C); Additional Mold Compound;
R5F364AMDFB#U0	R5F364AMDFB#30	Bond Wire Material Change (Au to Cu); Lead Frame Change (Frame A to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only)
R5F364AMNFB#30	No PN Change	Lead Frame Change (Frame A to Frame C); Additional Mold Compound;
R5F364AMNFB#U0	R5F364AMNFB#30	Bond Wire Material Change (Au to Cu); Lead Frame Change (Frame A to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only)
R5F36506DFB#30	No PN Change	Lead Frame Change (Frame A to Frame C); Additional Mold Compound;
R5F36506DFB#U0	R5F36506DFB#30	Bond Wire Material Change (Au to Cu); Lead Frame Change (Frame A to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only)
R5F36506NFB#30	No PN Change	Lead Frame Change (Frame A to Frame C); Additional Mold Compound;
R5F3650EDFB#30	No PN Change	Lead Frame Change (Frame A to Frame C); Additional Mold Compound;
R5F3650EDFB#U0	R5F3650EDFB#30	Bond Wire Material Change (Au to Cu); Lead Frame Change (Frame A to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only)
R5F3650ENFB#30	No PN Change	Lead Frame Change (Frame A to Frame C); Additional Mold Compound;
R5F3650KDFB#30	No PN Change	Lead Frame Change (Frame A to Frame C); Additional Mold Compound;
R5F3650KDFB#30	No PN Change	Lead Frame Change (Frame A to Frame C); Additional Mold Compound;
R5F3650KDFB#U0	R5F3650KDFB#30	Bond Wire Material Change (Au to Cu); Lead Frame Change (Frame A to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only)
R5F3650KDFB#UA	R5F3650KDFB#3A	Bond Wire Material Change (Au to Cu); Lead Frame Change (Frame A to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only)
R5F3650KNFB#30	No PN Change	Lead Frame Change (Frame A to Frame C); Additional Mold Compound;
R5F3650KNFB#U0	R5F3650KNFB#30	Bond Wire Material Change (Au to Cu); Lead Frame Change (Frame A to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only)
R5F3650MCDFB#30	No PN Change	Lead Frame Change (Frame A to Frame C); Additional Mold Compound;
R5F3650MDFB#30	No PN Change	Lead Frame Change (Frame A to Frame C); Additional Mold Compound;
R5F3650MNFB#30	No PN Change	Lead Frame Change (Frame A to Frame C); Additional Mold Compound;
R5F3650NCNFB#30	No PN Change	Lead Frame Change (Frame A to Frame C); Additional Mold Compound;
R5F3650NDFB#30	No PN Change	Lead Frame Change (Frame A to Frame C); Additional Mold Compound;
R5F3650NDFB#U0	R5F3650NDFB#30	Bond Wire Material Change (Au to Cu); Lead Frame Change (Frame A to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only)

Appendix A: Affected Part Numbers (cont.)

Booking Part Number	Replacement PN	Change Notes
R5F3650NNFB#30	No PN Change	Lead Frame Change (Frame A to Frame C); Additional Mold Compound;
R5F3650NNFB#U0	R5F3650NNFB#30	Bond Wire Material Change (Au to Cu); Lead Frame Change (Frame A to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only)
R5F3650RDFB#30	No PN Change	Additional Mold Compound;
R5F3650RNFB#U0	R5F3650RNFB#30	Bond Wire Material Change (Au to Cu); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only)
R5F3650TDFB#30	No PN Change	Additional Mold Compound;
R5F3650TDFB#U0	R5F3650TDFB#30	Bond Wire Material Change (Au to Cu); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only)
R5F3650TNFB#30	No PN Change	Additional Mold Compound;
R5F36CA6DFB#30	No PN Change	Lead Frame Change (Frame B to Frame C); Additional Mold Compound;
R5F36CA6NFB#U0	R5F36CA6NFB#30	Bond Wire Material Change (Au to Cu); Lead Frame Change (Frame B to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only)
R5F36CAENFB#30	No PN Change	Lead Frame Change (Frame B to Frame C); Additional Mold Compound;
R5F36CAKNFB#U0	R5F36CAKNFB#30	Bond Wire Material Change (Au to Cu); Lead Frame Change (Frame B to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only)
R5F36CAMDFB#30	No PN Change	Lead Frame Change (Frame B to Frame C); Additional Mold Compound;
R5F36CAMDFB#U0	R5F36CAMDFB#30	Bond Wire Material Change (Au to Cu); Lead Frame Change (Frame B to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only)
R5F36CAMNFB#30	No PN Change	Lead Frame Change (Frame B to Frame C); Additional Mold Compound;
R5F36CAMNFB#U0	R5F36CAMNFB#30	Bond Wire Material Change (Au to Cu); Lead Frame Change (Frame B to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only)

Appendix B: Change Summary

Item	Current	After Change
Bonding Wire	Cu	Cu Only
	Cu or Au	
	Au	
Lead Frame	Frame A	Frame C
	Frame B	
	Frame D	Frame E
Mold Compound	Compound A	Compound A or B
	Compound B	Compound B
Solder Paste	Sn	Sn Only
	SnCu	
Top Mark	-	Changed for Specific Devices
Assembly Factory	RSB: Renesas Semiconductor (Beijing) Co., Ltd.	RSB Only
	RSB: Renesas Semiconductor (Beijing) Co., Ltd ATJ: Amkor Technology Japan, Inc.	

Appendix C: Top Mark Change Diagrams

Figure1

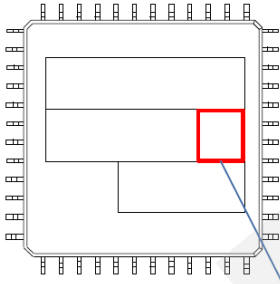
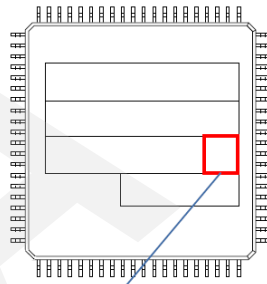


Figure2



The "Product Code" (2 characters) printed here will be changed.

Figure3

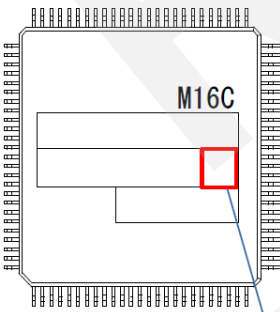
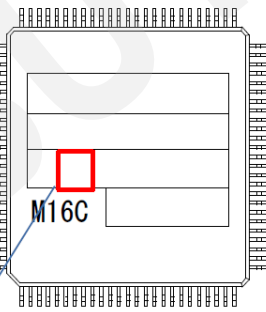
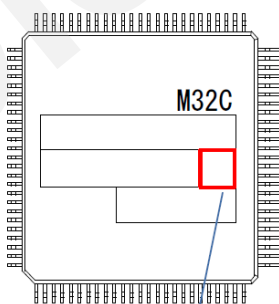


Figure4



The "Product Code" (2 characters) printed here will be changed.

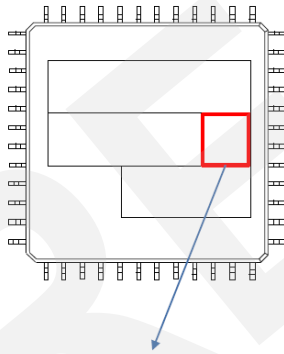
Figure5



The "Product Code" (2 characters) printed here will be changed.

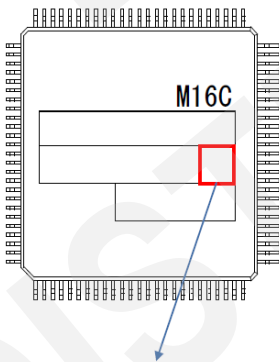
Appendix C: Top Mark Change Diagrams (cont.)

Figure6



The "Product Code" (2 characters) printed here will be changed.

Figure7



The "Product Code" (2 characters) printed here will be changed.